TOSHIBA 2SK3128

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ( $\pi$ -MOSVI)

# 2 S K 3 1 2 8

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

Low Drain-Source ON Resistance :  $R_{DS(ON)} = 9.5 \,\mathrm{m}\Omega$  (Typ.)

High Forward Transfer Admittance:  $|Y_{fS}| = 40 \text{ S}$  (Typ.)

Low Leakage Current :  $I_{DSS} = 100 \,\mu\text{A}$  (Max.) ( $V_{DS} = 30 \,\text{V}$ )

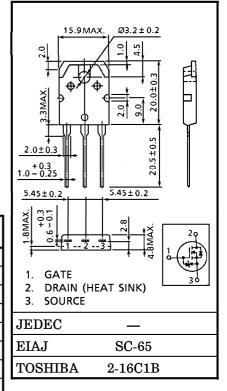
:  $V_{th} = 1.5 \sim 3.0 \text{ V}$ Enhancement-Mode

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$ 

#### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$v_{ m DSS}$	30	V	
Drain-Gate Voltage (RG	$v_{ m DGR}$	30	V	
Gate-Source Voltage	$v_{GSS}$	±20	V	
Drain Current	DC	$I_{\mathbf{D}}$	60	A
	Pulse	$I_{\mathrm{DP}}$	180	A
Drain Power Dissipation	$P_{\mathbf{D}}$	150	W	
Single Pulse Avalanche	EAS	411	mJ	
Avalanche Current	$I_{AR}$	60	A	
Repetitive Avalanche Er	$\mathrm{E}_{\mathrm{AR}}$	1.5	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Ra	$\mathrm{T}_{\mathrm{stg}}$	-55~150	°C	

# INDUSTRIAL APPLICATIONS Unit in mm



### THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R <sub>th (ch-c)</sub>	1.0	°C/W
Thermal Resistance, Channel to Ambient	R <sub>th (ch-a)</sub>	50	°C/W

#### Note:

- \* Repetitive rating; Pulse Width Limited by Max. junction temperature.
- \*\*  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 82  $\mu H$ ,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 60 A

This transistor is an electrostatic sensitive device. Please handle with caution.

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# ELECTRICAL CHARACTERISTICS (Ta = 25°C)

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CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	$I_{GSS}$	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$		_	±10	$\mu$ A
Drain Cut-of	f Current	$I_{ m DSS}$	$V_{DS} = 30 \text{ V}, \ V_{GS} = 0 \text{ V}$	_	_	100	$\mu$ <b>A</b>
Drain-Source Voltage	Breakdown	V (BR) DSS	$I_D = 10 \text{ mA}, \ V_{GS} = 0 \text{ V}$	30	_	_	V
Gate Thresho	old Voltage	$V_{ m th}$	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.5	_	3.0	V
Drain-Source	ON Resistance	R <sub>DS</sub> (ON)	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		9.5	12	$\mathbf{m}\Omega$
Forward Train Admittance	nsfer	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 30 \text{ A}$	20	40	_	S
Input Capacitance Reverse Transfer Capacitance		$\mathrm{c}_{\mathrm{iss}}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1 MHz	_	2300	<u> </u>	pF
		C <sub>rss</sub>		_	380	_	
Output Capa	citance	$C_{OSS}$		_	1100	_	
Switching Time	Rise Time	t <sub>r</sub>	$V_{GS} = 0 \text{ V}$ $V_{GS} = 0 \text{ V}$ $V_{DD} = 30 \text{ A}$ $V_{DU} = 1.0 \Omega$ $V_{DD} = 30 \text{ V}$ $V_{IN} : t_r, t_f < 5 \text{ ns},$ $Duty \leq 1\%, t_w = 10 \mu\text{s}$		12	_	
	Turn-on Time	t <sub>on</sub>			25	_	ns
	Fall Time	$t_f$		1	75	_	115
	Turn-off Time	t <sub>off</sub>		_	200	_	
Total Gate Charge (Gate-Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 24 \text{ V}, V_{GS} = 10 \text{ V}$	_	66	_	$_{ m nC}$
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_D = 60 A$		45	_	] "C
Gate-Drain ("Miller") Charge		$ m Q_{gd}$			21	_	

# SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	60	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	180	A
Diode Forward Voltage	${ m v_{DSF}}$	$I_{DR} = 60 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.5	V
Reverse Recovery Time	${ m t_{rr}}$	$I_{DR} = 60 \text{ A}, V_{GS} = 0 \text{ V}$		150	_	ns
Reverse Recovery Charge	$Q_{\mathbf{rr}}$	$\mathrm{dI_{DR}}$ / $\mathrm{dt} = 50\mathrm{A}$ / $\mu\mathrm{s}$	_	0.26		$\mu$ C

## MARKING

